

Features

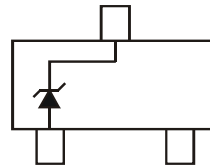
- Planar Die Construction
- 350mW Power Dissipation
- Zener Voltages from 2.4V - 51V
- Ideally Suited for Automated Assembly Processes
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 0.008 grams (approximate)

SOT23

Top View



Device Schematic

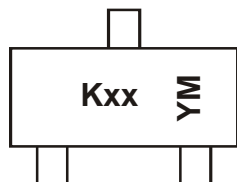
Ordering Information (Note 5)

Part Number	Qualification	Case	Packaging
(Type Number)-7-F	Commercial	SOT23	3,000/Tape & Reel
(Type Number)Q-7-F	Automotive	SOT23	3,000/Tape & Reel
(Type Number)-13-F	Commercial	SOT23	10,000/Tape & Reel
(Type Number)Q-13-F	Automotive	SOT23	10,000/Tape & Reel

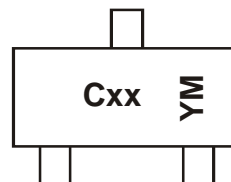
*For (Type Number), please see the Electrical Characteristics Table. Example: 6.2V Zener = BZX84C6V2-7-F.

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. BZX84C2V4-BZX84C39 products manufactured with Date Code OW (week 42, 2009) and newer are built with Green Molding Compound. BZX84C2V4-BZX84C39 products manufactured prior to Date Code OW are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants. BZX84C43-BZX84C51 products manufactured with Date Code V9 (week 33, 2008) and newer are built with Green Molding Compound. BZX84C43-BZX84C51 products manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.
 5. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



K = SAT (Shanghai Assembly / Test site)
 xx = Product Type Marking Code
 (See Electrical Characteristics Table)
 YM = Date Code Marking
 Y = Year (ex: Z = 2012)
 M = Month (ex: 9 = September)



C = CAT (Chengdu Assembly / Test site)
 xx = Product Type Marking Code
 (See Electrical Characteristics Table)
 YM = Date Code Marking
 Y = Year (ex: Z = 2012)
 M = Month (ex: 9 = September)

Date Code Key

Year	1998	...	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017
Code	J	...	N	P	R	S	T	U	V	W	X	Y	Z	A	B	C	D	E
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec						
Code	1	2	3	4	5	6	7	8	9	O	N	D						

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Forward Voltage @ I _F = 10mA	V _F	0.9	V

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	300	mW
Power Dissipation (Note 7)	P _D	350	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	R _{θJA}	417	°C/W
Thermal Resistance, Junction to Ambient Air (Note 7)	R _{θJA}	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Type Number	Marking Code	Zener Voltage Range (Note 8)				Maximum Zener Impedance f = 1KHz			Maximum Reverse Current (Note 8)		Temperature Coefficient @ I _{ZT} mV/°C	
		V _Z @ I _{ZT}			I _{ZT} (mA)	Z _{zT} @ I _{ZT} (Ω)	Z _{zK} @ I _{ZK}		I _R (μA)	V _R (V)	Min	Max
		Nom (V)	Min (V)	Max (V)			(Ω)	(mA)				
BZX84C2V4	ZB	2.4	2.2	2.6	5.0	100	600	1.0	50	1.0	-3.5	0
BZX84C2V7	ZC	2.7	2.5	2.9	5.0	100	600	1.0	20	1.0	-3.5	0
BZX84C3V0	ZD	3.0	2.8	3.2	5.0	95	600	1.0	10	1.0	-3.5	0
BZX84C3V3	ZE	3.3	3.1	3.5	5.0	95	600	1.0	5.0	1.0	-3.5	0
BZX84C3V6	ZF	3.6	3.4	3.8	5.0	90	600	1.0	5.0	1.0	-3.5	0
BZX84C3V9	ZG	3.9	3.7	4.1	5.0	90	600	1.0	3.0	1.0	-3.5	0
BZX84C4V3	ZH	4.3	4.0	4.6	5.0	90	600	1.0	3.0	1.0	-3.5	0
BZX84C4V7	ZI	4.7	4.4	5.0	5.0	80	500	1.0	3.0	2.0	-3.5	0.2
BZX84C5V1	Z2	5.1	4.8	5.4	5.0	60	480	1.0	2.0	2.0	-2.7	1.2
BZX84C5V6	Z3	5.6	5.2	6.0	5.0	40	400	1.0	1.0	2.0	-2.0	2.5
BZX84C6V2	Z4	6.2	5.8	6.6	5.0	10	150	1.0	3.0	4.0	0.4	3.7
BZX84C6V8	Z5	6.8	6.4	7.2	5.0	15	80	1.0	2.0	4.0	1.2	4.5
BZX84C7V5	Z6	7.5	7.0	7.9	5.0	15	80	1.0	1.0	5.0	2.5	5.3
BZX84C8V2	Z7	8.2	7.7	8.7	5.0	15	80	1.0	0.7	5.0	3.2	6.2
BZX84C9V1	Z8	9.1	8.5	9.6	5.0	15	100	1.0	0.5	6.0	3.8	7.0
BZX84C10	Z9	10	9.4	10.6	5.0	20	150	1.0	0.2	7.0	4.5	8.0
BZX84C11	Y1	11	10.4	11.6	5.0	20	150	1.0	0.1	8.0	5.4	9.0
BZX84C12	Y2	12	11.4	12.7	5.0	25	150	1.0	0.1	8.0	6.0	10.0
BZX84C13	Y3	13	12.4	14.1	5.0	30	170	1.0	0.1	8.0	7.0	11.0
BZX84C15	Y4	15	13.8	15.6	5.0	30	200	1.0	0.1	10.5	9.2	13.0
BZX84C16	Y5	16	15.3	17.1	5.0	40	200	1.0	0.1	11.2	10.4	14.0
BZX84C18	Y6	18	16.8	19.1	5.0	45	225	1.0	0.1	12.6	12.4	16.0
BZX84C20	Y7	20	18.8	21.2	5.0	55	225	1.0	0.1	14.0	14.4	18.0
BZX84C22	Y8	22	20.8	23.3	5.0	55	250	1.0	0.1	15.4	16.4	-
BZX84C24	Y9	24	22.8	25.6	5.0	70	250	1.0	0.1	16.8	18.4	-
BZX84C27	YA	27	25.1	28.9	2.0	80	300	0.5	0.1	18.9	21.4	-
BZX84C30	YB	30	28.0	32.0	2.0	80	300	0.5	0.1	21.0	24.4	-
BZX84C33	YC	33	31.0	35.0	2.0	80	325	0.5	0.1	23.1	27.4	-
BZX84C36	YD	36	34.0	38.0	2.0	90	350	0.5	0.1	25.2	30.4	-
BZX84C39	YE	39	37.0	41.0	2.0	130	350	0.5	0.1	27.3	33.4	-
BZX84C43	YF	43	40.0	46.0	2.0	150	375	0.5	0.1	30.1	37.6	-
BZX84C47	YG	47	44.0	50.0	2.0	170	375	0.5	0.1	32.9	42.0	-
BZX84C51	YH	51	48.0	54.0	2.0	180	400	0.5	0.1	35.7	46.6	-

Notes: 6. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com>.
7. Valid provided the terminals are kept at ambient temperature.
8. Short duration pulse test used to minimize self-heating effect.

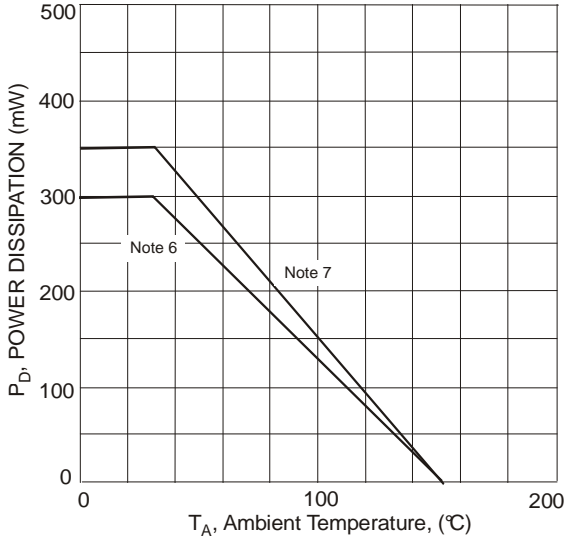


Fig. 1 Power Derating Curve

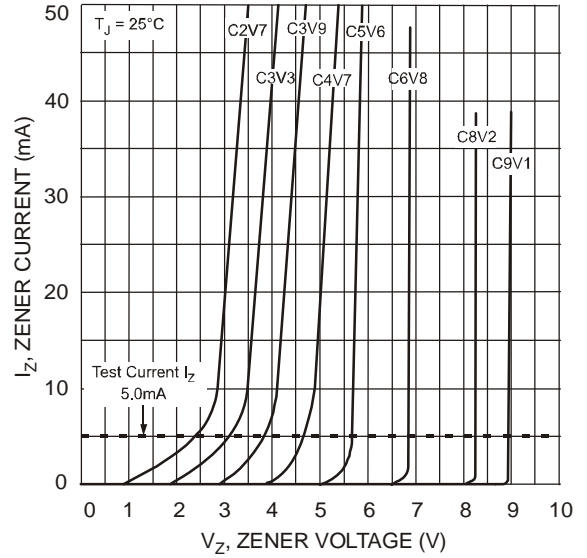


Fig. 2 Typical Zener Breakdown Characteristics

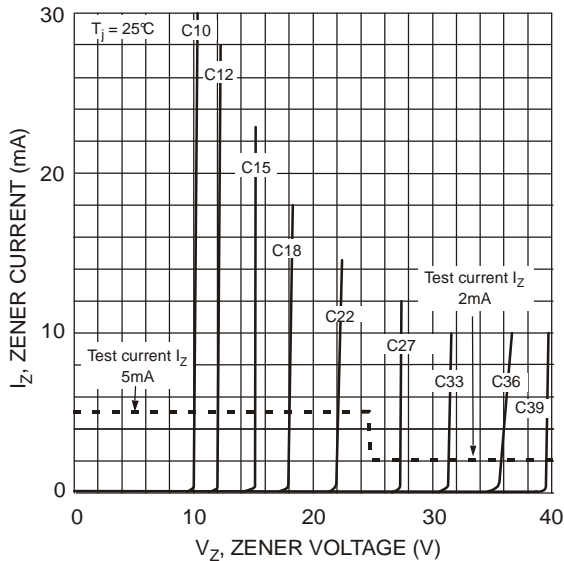


Fig. 3 Typical Zener Breakdown Characteristics

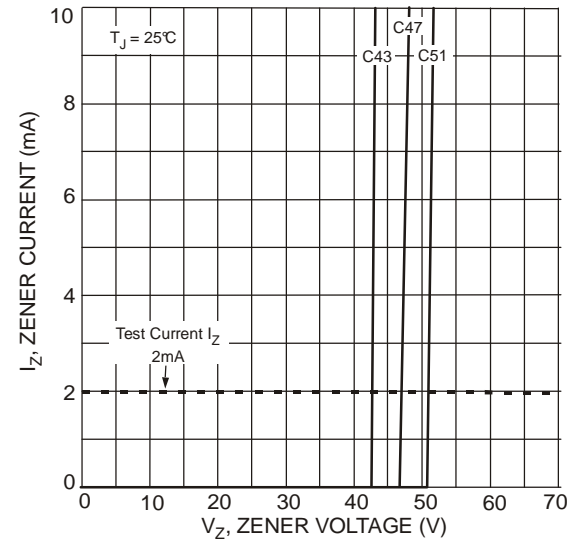


Fig. 4 Typical Zener Breakdown Characteristics

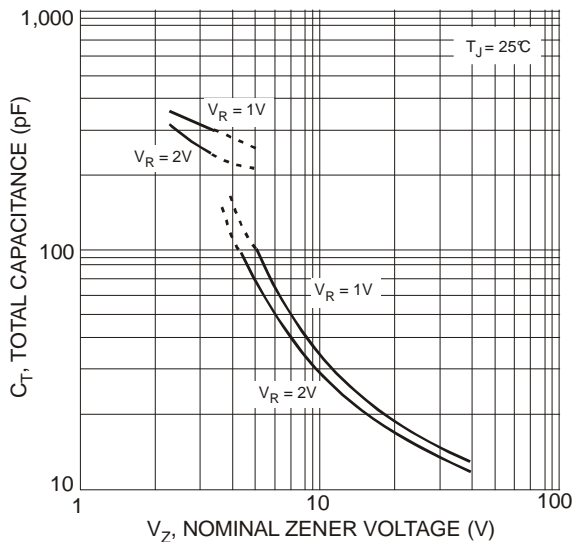


Fig. 5 Typical Total Capacitance vs. Nominal Zener Voltage

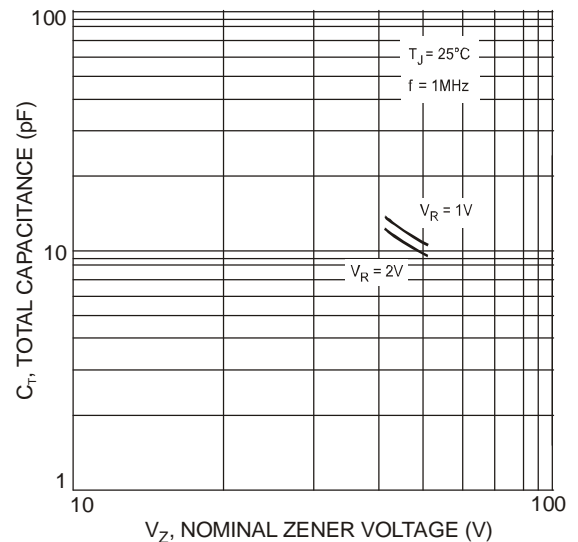
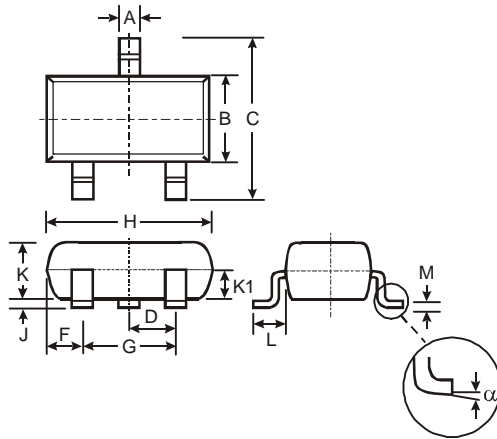


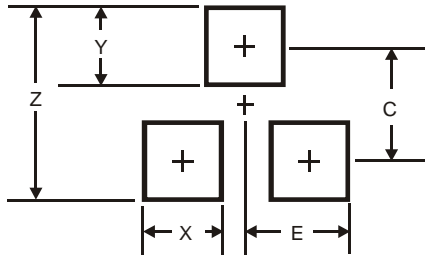
Fig. 6 Typical Total Capacitance vs. Nominal Zener Voltage

Package Outline Dimensions



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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